

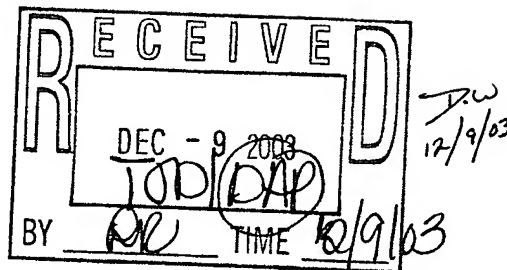
Exhibit G



Micron Technology, Inc.
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December 8, 2003

Tom D'Amico
Dickstein, Shapiro, Morin
& Oshinsky
2101 L Street N.W.
Washington, D.C. 20037



Re: Micron Docket # 03-0953
Your Ref. # M4065.1005

Dear Tom:

In accordance with the inventors request, please find the transformations for the above referenced draft. Please revise as stated and provide me with an amended draft.

Feel free to let me know if you have any questions.

Very truly yours,

Stacy L. Summers
Patent Assistant

Phone: 208/368-4591
Fax: 208/368-5606

Exhibit H

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December 9, 2003

BY FEDERAL EXPRESS

Ms. Stacy L. Summers
Patent Assistant
Micron Technology, Inc.
8000 S. Federal Way
Boise, ID 83707

**PRIVILEGED AND CONFIDENTIAL:
ATTORNEY-CLIENT COMMUNICATION**

Re: Proposed U.S. Patent Application
Title: A DIE PACKAGE HAVING AN ADHESIVE FLOW RESTRICTION
AREA
Re: Inventors: Bret K. Street et al.
Micron References: 03-0953
Our Reference: M4065.1005/P1005


Dear Stacy:

Enclosed please find five copies of an executable draft for Micron's patent application entitled "A DIE PACKAGE HAVING AN ADHESIVE FLOW RESTIRCTION AREA."

We are also enclosing signature papers including a declaration, an assignment and a power of attorney by assignee document. Accordingly, please have the inventors review the application, sign the declaration and assignment, and have all of the executable documents returned to us as soon as possible.

Please direct any comments or questions on the draft to Dipu A. Doshi at (202) 572-2604. If you have any questions, please do not hesitate to call.

Sincerely yours,


Thomas J. D'Amico

TJD/DAD/jlb

Enclosures (five copies of the specification and figures,
one copy of the executable papers)